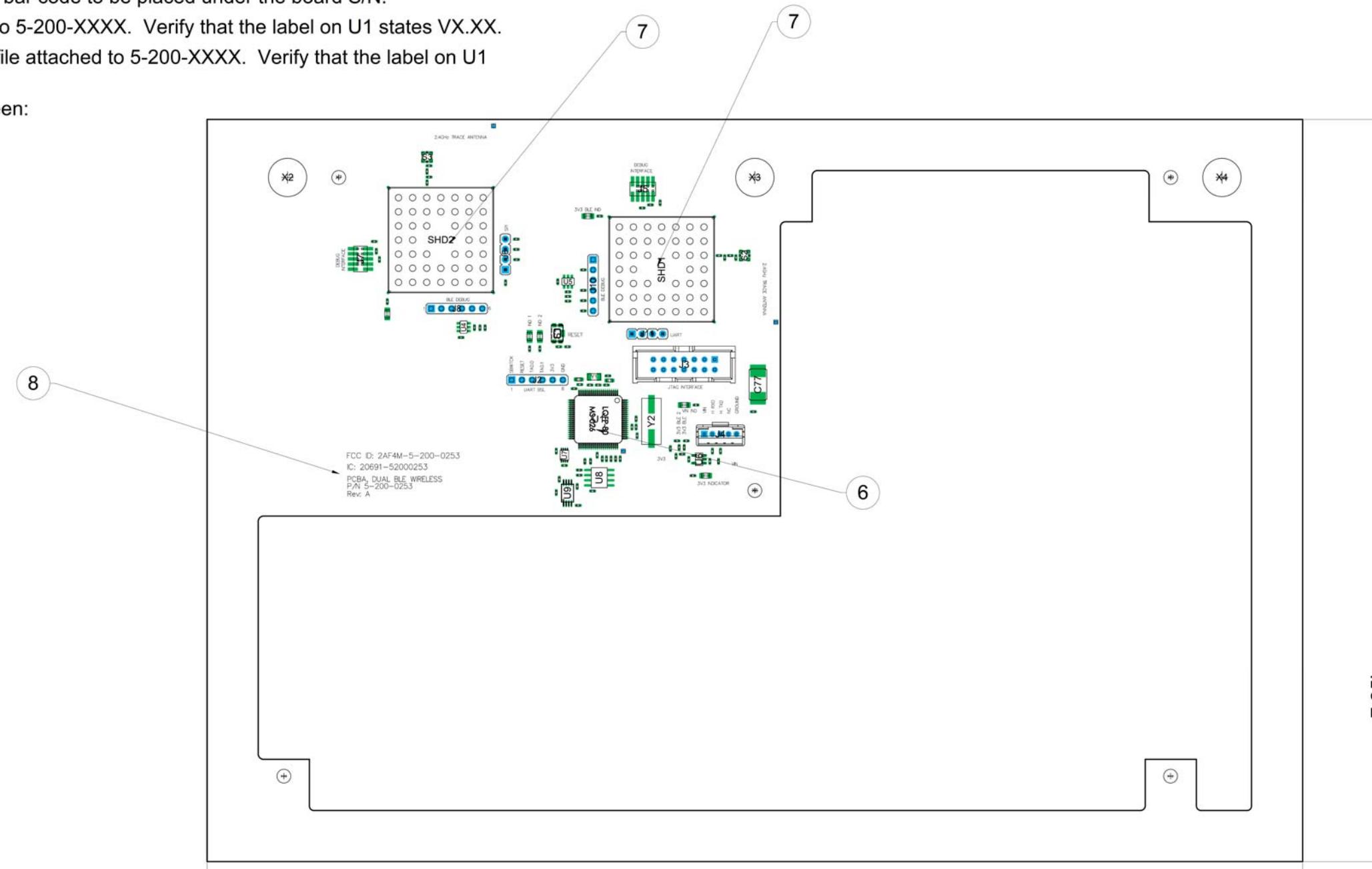
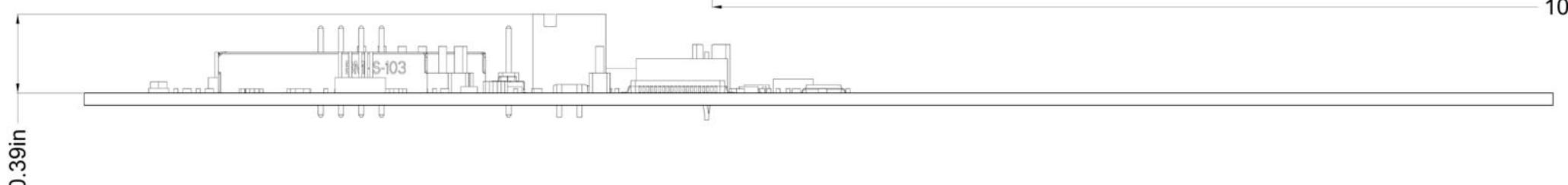


1. Assemble and Solder Per IPC-A-610 Class 2, RoHS Compliant Process.
 2. Assembly to be Packaged and Transported. To be permanently marked in the appropriate area on the primary side of assembly.
 3. Assembly to be packaged and transported in a conductive and shielded container and handled in a static safe work area.
 4. BOM for this assembly is released in Agile by the same part number and revision level.

5 Board Serial Number Label to be applied at this location. Orientation as indicated. Each board shall have a new Serial Number and corresponding bar code to be placed under the board S/N.
 6 Program U1 with programming file attached to 5-200-XXXX. Verify that the label on U1 states VX.XX.
 7 Program SDH1 and SDH2 with programming file attached to 5-200-XXXX. Verify that the label on U1 states VX.XX.
 8 Following Text needs to be in the top silkscreen:
 FCC ID: 2AF4M-5-200-0253
 IC: 20691-52000253



View from Left side (Scale 2.7753)



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UNLESS OTHERWISE SPECIFIED	NAME	DATE
DIMENSIONS ARE IN INCHES	DRAWN	6/12/2018
FRACTIONAL	CHECKED	
ANGULAR: MACH. BEND \pm	ENG APPR.	
TWO PLACE DECIMAL \pm	MFG APPR.	
THREE PLACE DECIMAL \pm	INTERPRET GEOMETRIC	
	TOLERANCING PER	
	Q.A.	
	COMMENTS:	
	MATERIAL	
	NEXT ASSY	USED ON
	FINISH	
	APPLICATION	DO NOT SCALE DRAWING

Midmark Corporation
PCBA, Dual BLE Wireless
DWG. NO. 5-200-0253-XX
REV A
SCALE: 1:1 WEIGHT: SHEET 1 OF 1